

Amendments to and Listing of the Claims:

Please cancel claims 1, 3-15, 17, 18, 26-33, and 35, without prejudice. Please amend claim 19 as indicated below, wherein strikethrough indicates deletion and underlining indicates addition. This listing of claims will replace all prior versions and listings of claims in the application.

1.-18. (Cancelled)

19. (Currently amended) A method for making a conductive adhesive composition comprising the steps of:

mixing a liquid epoxy precursor and a polymer additive to form a first mixture;
stirring said first mixture at at least room temperature until it forms a first homogeneous blend;
adding a anhydride curing additive to said first homogeneous blend to form a second mixture;
stirring said second mixture at at least room temperature until it forms a second homogeneous blend;
adding a epoxy curing catalyst to said second homogeneous blend to form a third mixture;
stirring said third mixture until it forms a third homogeneous blend, and
adding conductive filler particles in said third homogeneous blend to form a conductive adhesive composition,
wherein:
said liquid epoxy precursor is a soluble mixture of 1,3-bis(glycidoxypentyl) tetramethyl disiloxane and said polymer additive is ~~poly (ABA-glycidyl methacrylate oligomer)~~ oligomeric ABA-glycidyl methacrylate diester and said first mixture is prepared by heating with stirring at approximately 50° C.;
said anhydride curing additive is HHPA, or a mixture of HHPA and MeHHPA;

said epoxy curing catalyst is nonylphenol+ethylene glycol, and the tertiary amine 2,4,6-tris(dimethylamino-methyl)phenol; and

said conductive filler particles are Au-coated Ag, Pd-coated Ag filler, Ag flake, or a combination thereof blended to form screenable conductive adhesive paste.

20.-35 (Cancelled)